

# SHINDENGEN

## HVX-2 Series Power MOSFET

N-Channel Enhancement type

**2SK2676**

( F10W90HVX2 )

**900V 10A**

### FEATURES

- Input capacitance ( $C_{iss}$ ) is small.  
Especially, input capacitance at 0 bias is small.
- The static  $R_{ds(on)}$  is small.
- The switching time is fast.
- Avalanche resistance guaranteed.

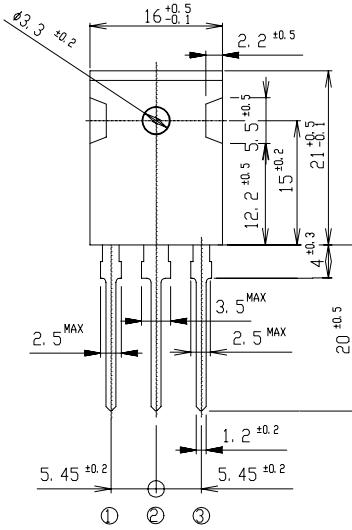
### APPLICATION

- Switching power supply of AC 240V input
- High voltage power supply
- Inverter

### OUTLINE DIMENSIONS

Case : MTO-3P

(Unit : mm)



①: G

②: D

③: S

④: D

### RATINGS

#### ● Absolute Maximum Ratings (T<sub>c</sub> = 25°C)

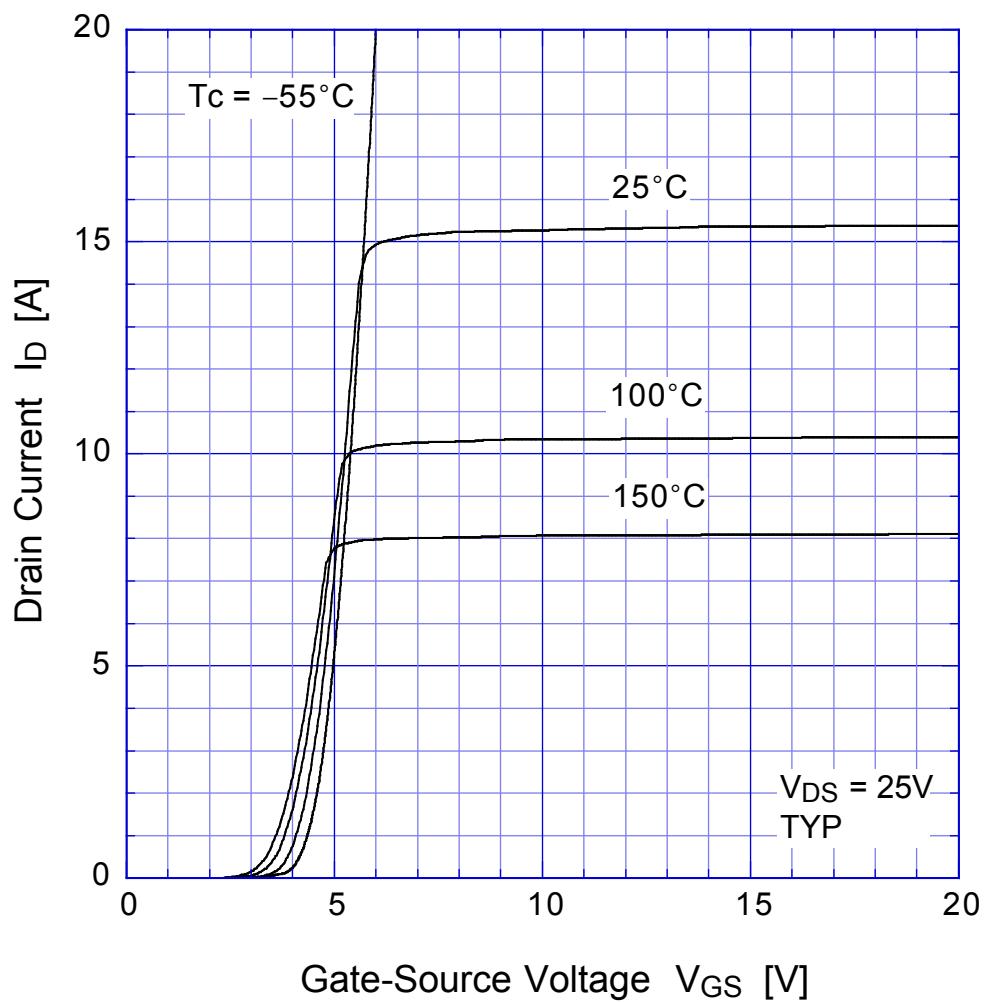
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	T <sub>stg</sub>		-55~150	°C
Channel Temperature	T <sub>ch</sub>		150	
Drain-Source Voltage	V <sub>DSS</sub>		900	V
Gate-Source Voltage	V <sub>GSS</sub>		±30	
Continuous Drain Current (DC)	I <sub>D</sub>		10	A
Continuous Drain Current (Peak)	I <sub>DP</sub>	Pulse width ≤ 10 μ s, Duty cycle ≤ 1/100	20	
Continuous Source Current (DC)	I <sub>S</sub>		10	
Total Power Dissipation	P <sub>T</sub>		120	W
Repetitive Avalanche Current	I <sub>AR</sub>	T <sub>ch</sub> = 150°C	10	A
Single Avalanche Energy	E <sub>AS</sub>	T <sub>ch</sub> = 25°C	260	mJ
Repetitive Avalanche Energy	E <sub>AR</sub>	T <sub>ch</sub> = 25°C	26	
Mounting Torque	T <sub>OR</sub>	( Recommended torque : 0.5 N·m )	0.8	N·m

●Electrical Characteristics T<sub>c</sub> = 25°C

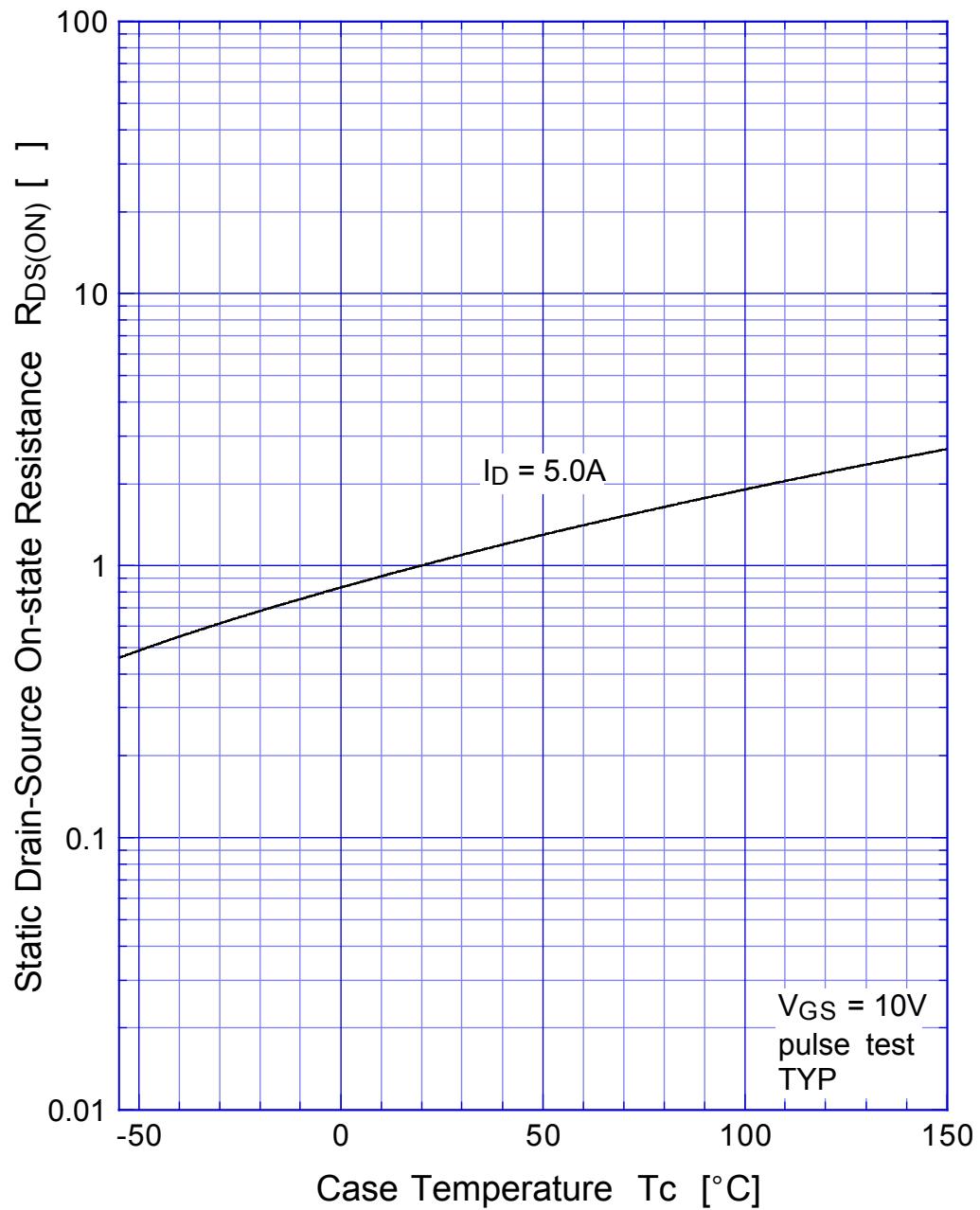
Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	ID = 1mA, VGS = 0V	900			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	VDS = 900V, VGS = 0V			250	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	VGS = ±30V, VDS = 0V			±0.1	
Forward Transconductance	g <sub>fS</sub>	ID = 5A, VDS = 10V	4.8	8.0		S
Static Drain-Source On-state Resistance	R <sub>D(S)ON</sub>	ID = 5A, VGS = 10V		1.05	1.4	Ω
Gate Threshold Voltage	V <sub>TH</sub>	ID = 1mA, VDS = 10V	2.5	3.0	3.5	V
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	IS = 5A, VGS = 0V			1.5	
Thermal Resistance	θ <sub>jc</sub>	junction to case			1.04	°C/W
Total Gate Charge	Q <sub>g</sub>	VDD = 400V, VGS = 10V, ID = 10A		90		nC
Input Capacitance	C <sub>iss</sub>	VDS = 25V, VGS = 0V, f = 1MHz		2150		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			50		
Output Capacitance	C <sub>oss</sub>			210		
Turn-On Time	t <sub>on</sub>	ID = 5A, RL = 30Ω, VGS = 10V		140	250	ns
Turn-Off Time	t <sub>off</sub>			440	740	

# 2SK2676

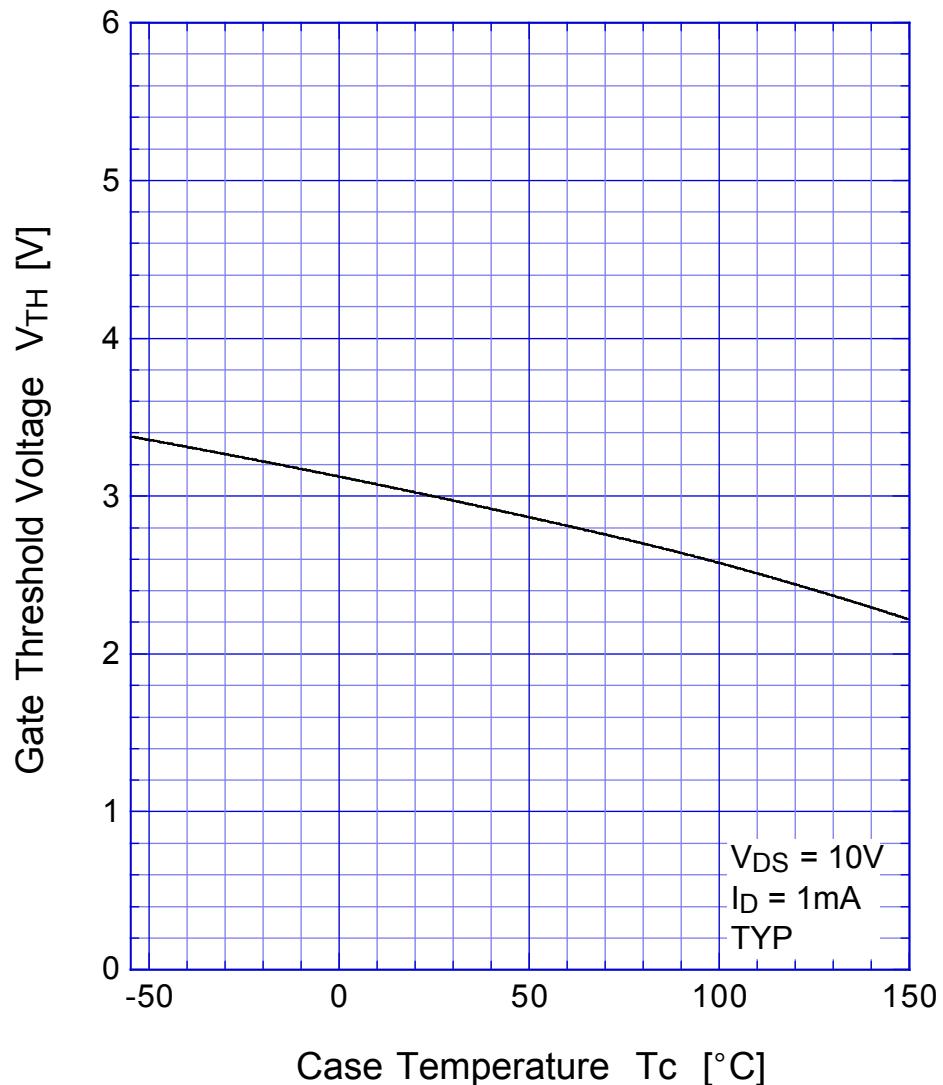
## Transfer Characteristics



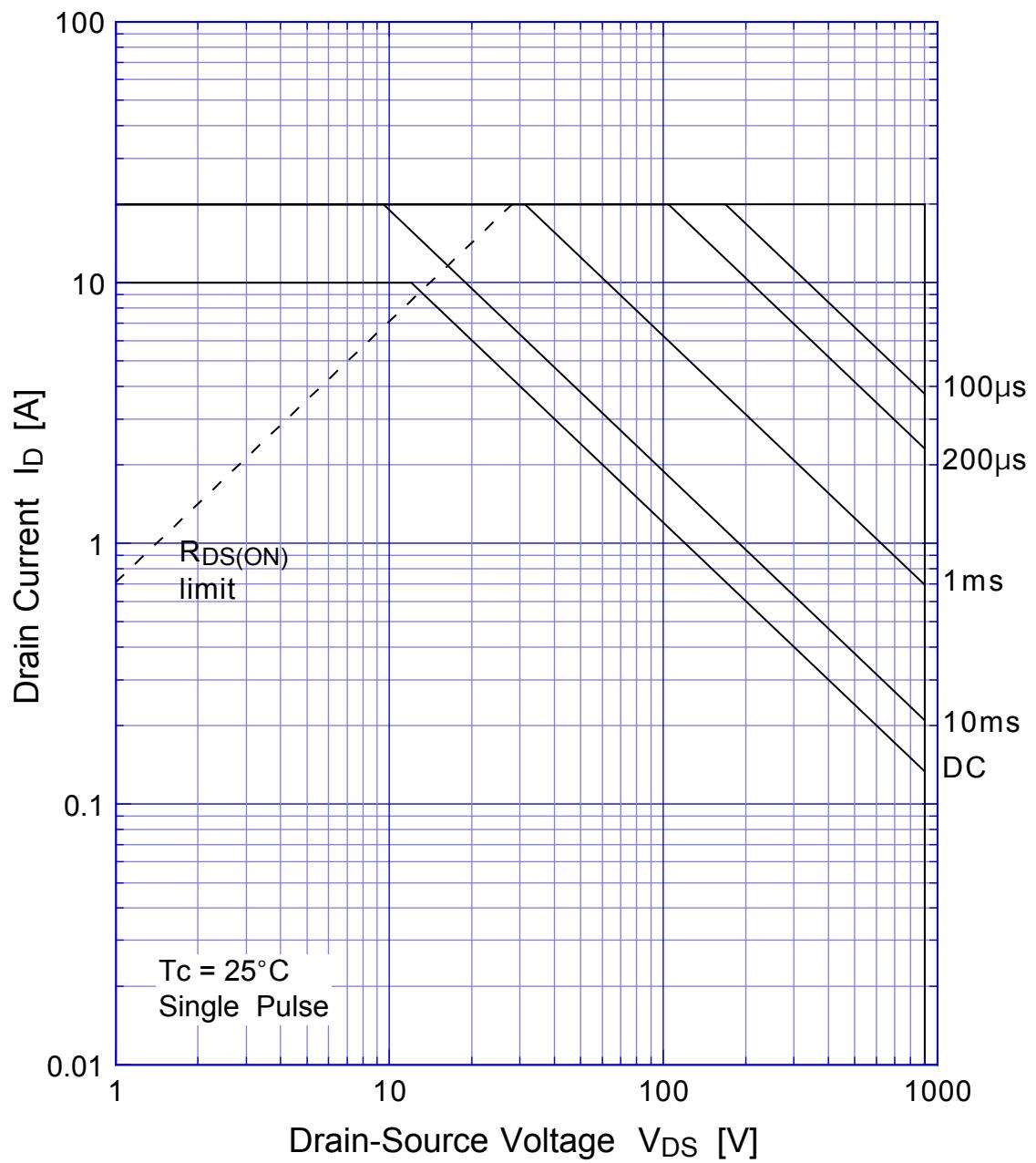
## 2SK2676 Static Drain-Source On-state Resistance



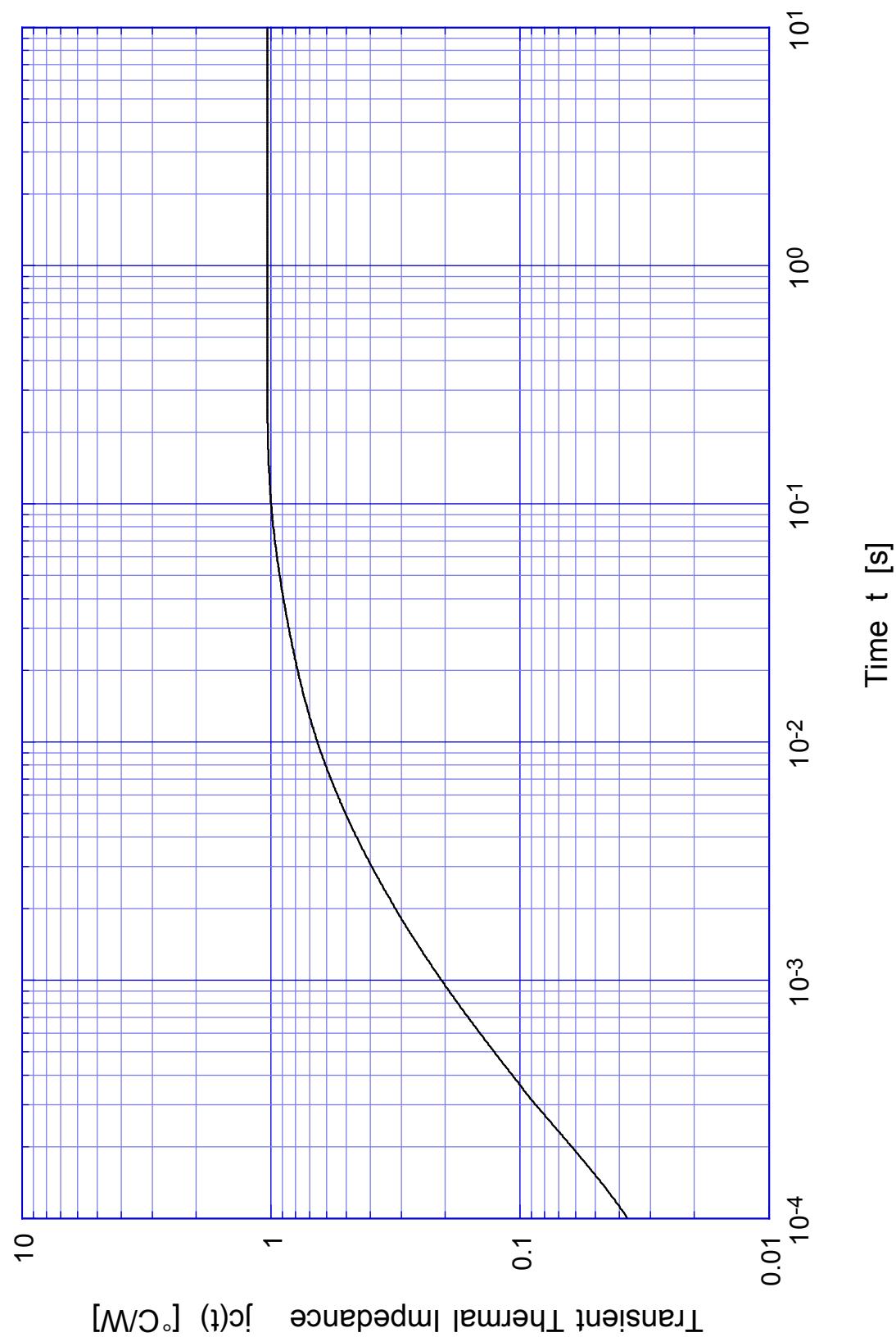
## 2SK2676 Gate Threshold Voltage



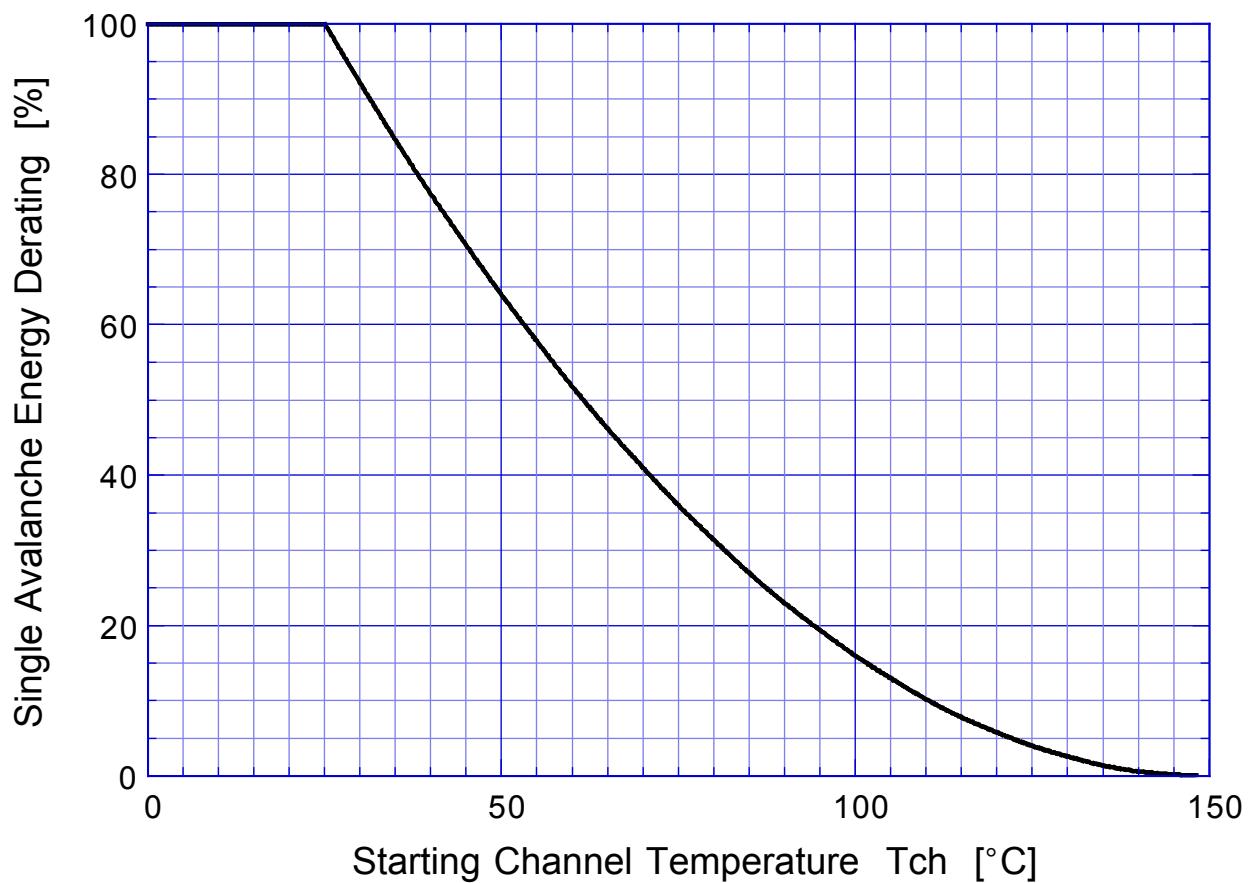
## 2SK2676 Safe Operating Area



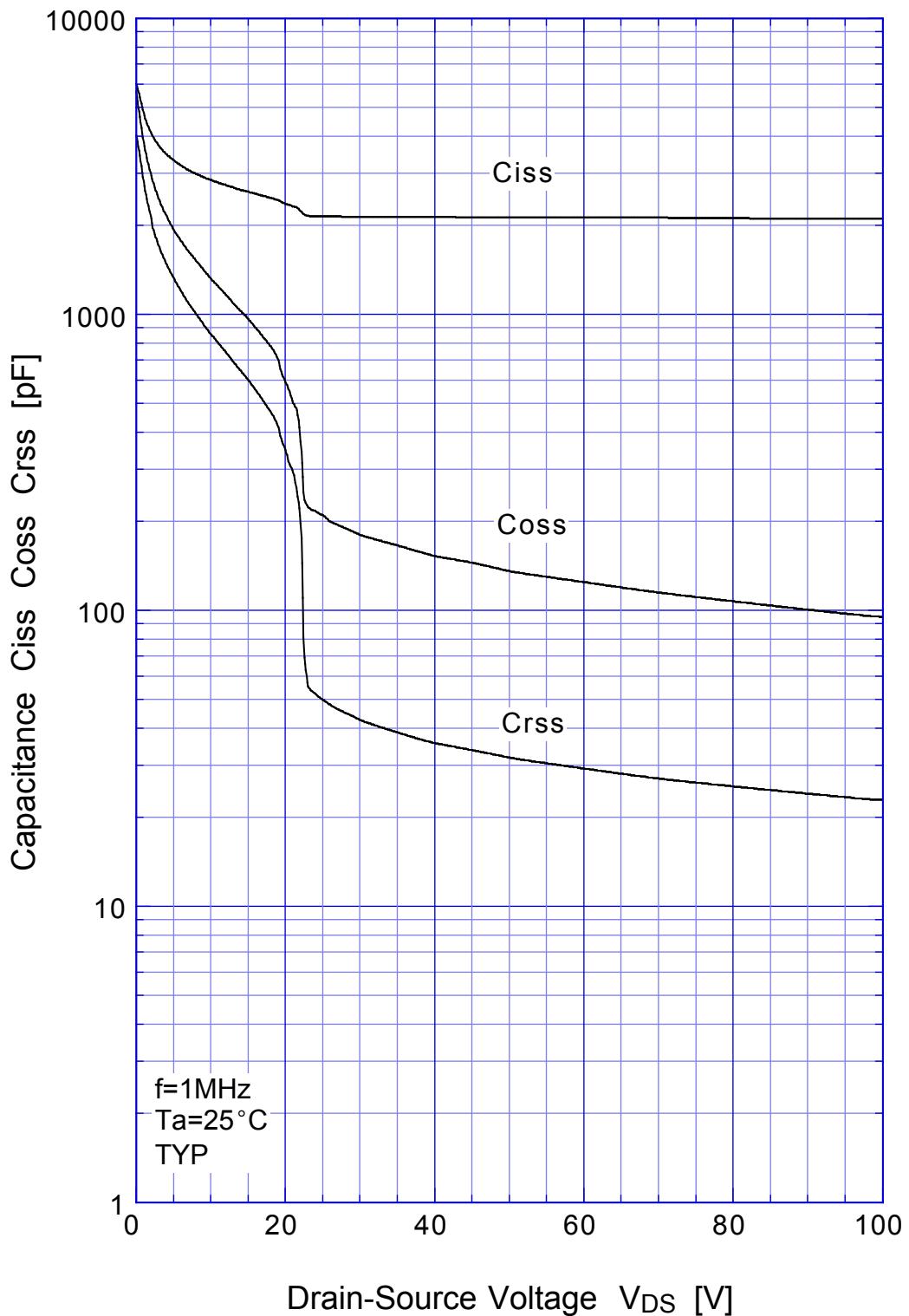
## 2SK2676 Transient Thermal Impedance



## **2SK2676 Single Avalanche Energy Derating**

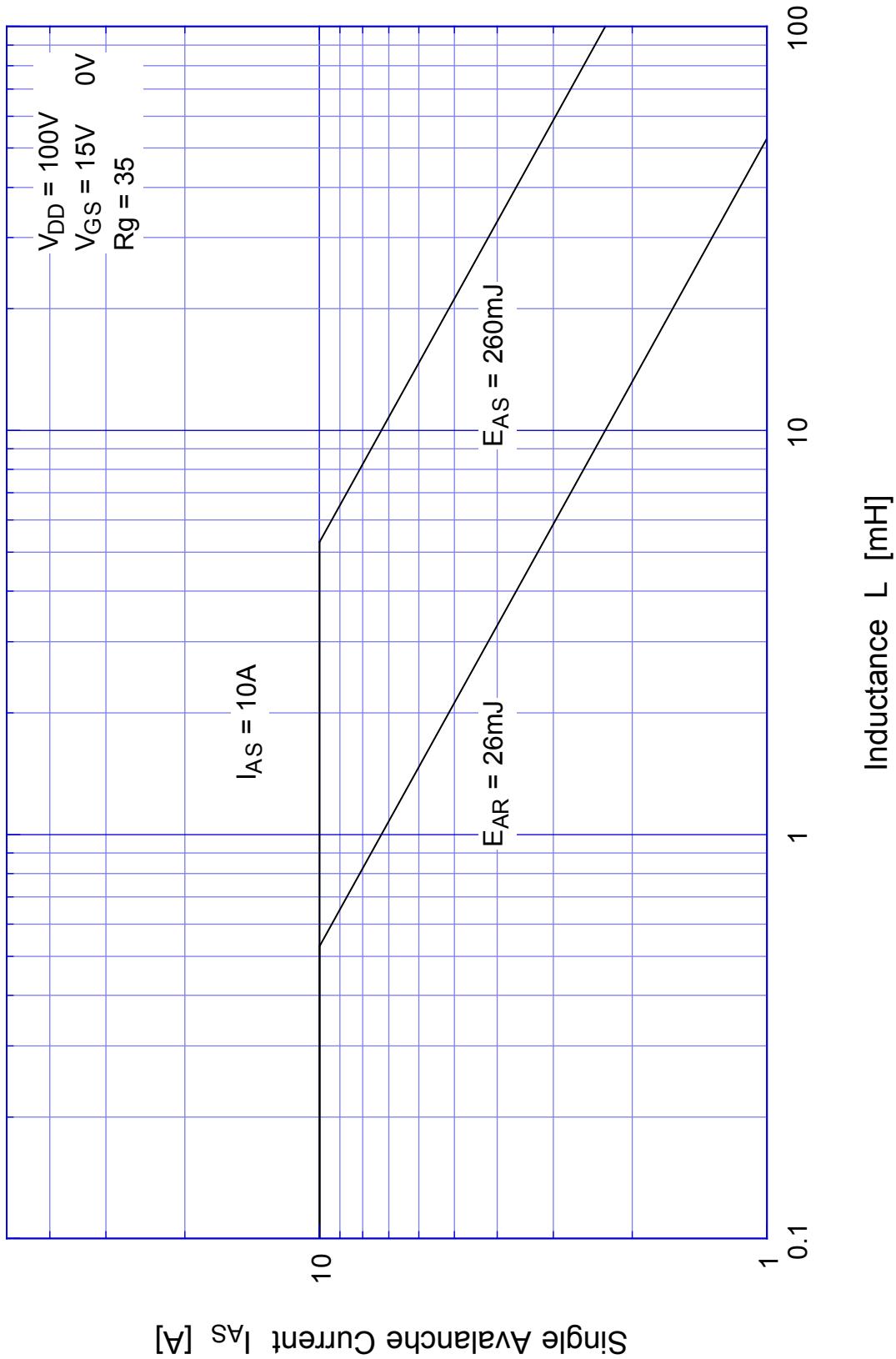


2SK2676 Capacitance



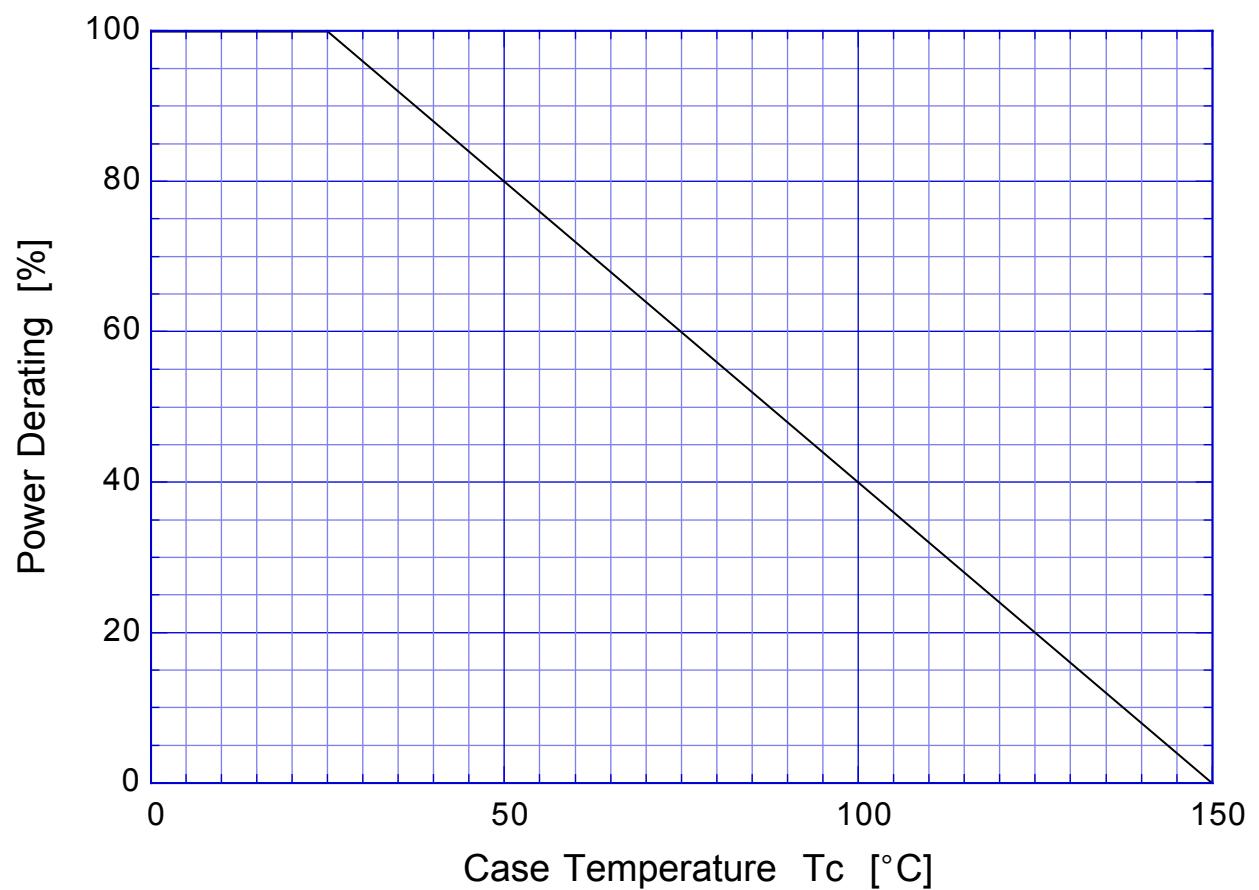
## 2SK2676 Single Avalanche Current - Inductive Load

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**2SK2676**

Power Derating



## 2SK2676

### Gate Charge Characteristics

